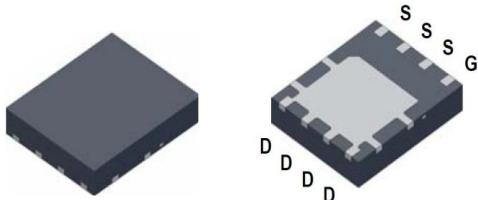


# PK501BA

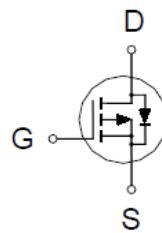
## P-Channel Logic Level Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
-30V	7mΩ @ $V_{GS} = -10V$	-43A



PDFN 5x6P



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 25$	
Continuous Drain Current	$I_D$	-43	A
		-27	
		-13	
		-10	
		-110	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-38	mJ
Avalanche Current	$I_{AS}$	72	
Avalanche Energy	$E_{AS}$	25	W
Power Dissipation	$P_D$	10	
		2.2	
		1.4	
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

# PK501BA

## P-Channel Logic Level Enhancement Mode MOSFET

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	R <sub>θJA</sub>		56	°C / W
Junction-to-Case	R <sub>θJC</sub>		5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> = 25°C. The value in any given application depends on the user's specific board design.

### ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1	-1.5	-3	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±25V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -24V, V <sub>GS</sub> = 0V			-1	uA
		V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V , T <sub>J</sub> = 125 °C			-10	
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -13A		5.7	7	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -13A		8.4	12	
Forward Transconductance <sup>1</sup>	g <sub>f</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -13A		40		S
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -15V, f = 1MHz		2822		pF
Output Capacitance	C <sub>oss</sub>			452		
Reverse Transfer Capacitance	C <sub>rss</sub>			364		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1MHz		4		Ω
Total Gate Charge <sup>2</sup>	Q <sub>g(VGS=-10V)</sub>	V <sub>DS</sub> = -15V, I <sub>D</sub> = -13A		60		nC
	Q <sub>g(VGS=-4.5V)</sub>			30		
Gate-Source Charge <sup>2</sup>	Q <sub>gs</sub>			6.1		
Gate-Drain Charge <sup>2</sup>	Q <sub>gd</sub>			14		
Turn-On Delay Time <sup>2</sup>	t <sub>d(on)</sub>	V <sub>DS</sub> = -15V, I <sub>D</sub> ≈ -13A, V <sub>GS</sub> = -10V, R <sub>GS</sub> = 6Ω		39		nS
Rise Time <sup>2</sup>	t <sub>r</sub>			26		
Turn-Off Delay Time <sup>2</sup>	t <sub>d(off)</sub>			161		
Fall Time <sup>2</sup>	t <sub>f</sub>			100		

# PK501BA

## P-Channel Logic Level Enhancement Mode MOSFET

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ )						
Continuous Current	$I_S$				19	A
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = -13\text{A}, V_{GS} = 0\text{V}$			-1.3	V
Reverse Recovery Time	$t_{rr}$	$I_F = -13\text{A}, dI_F/dt = 100\text{A} / \mu\text{s}$		23		nS
Reverse Recovery Charge	$Q_{rr}$			6		nC

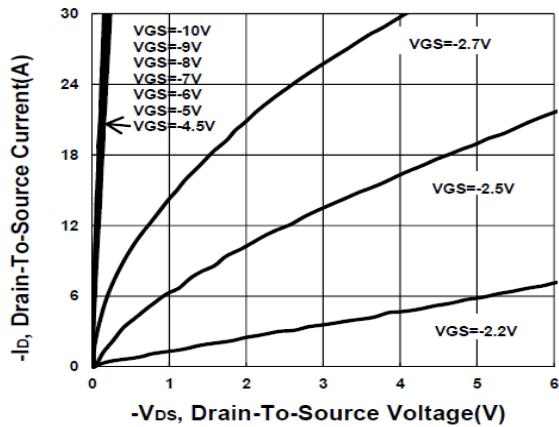
<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

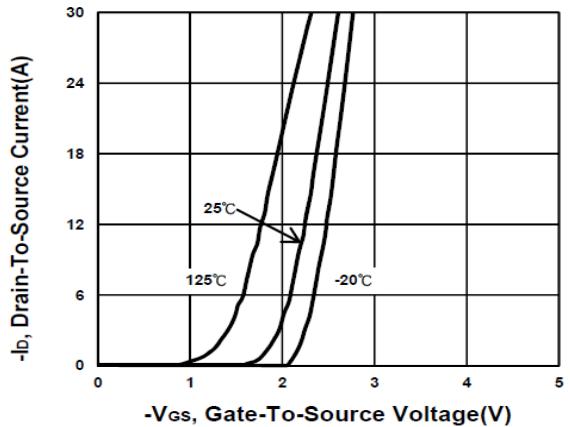
## PK501BA

### P-Channel Logic Level Enhancement Mode MOSFET

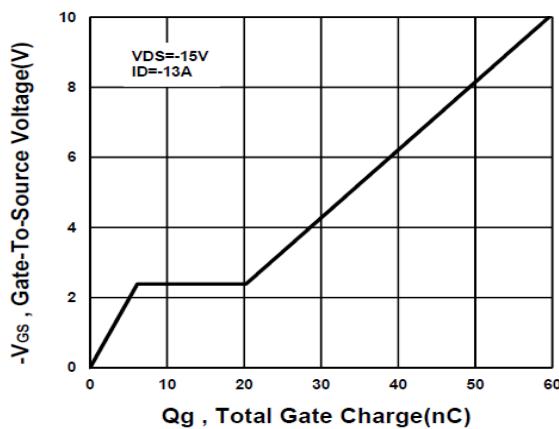
**Output Characteristics**



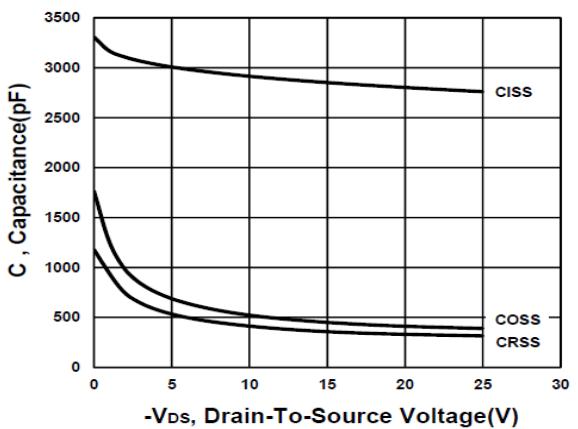
**Transfer Characteristics**



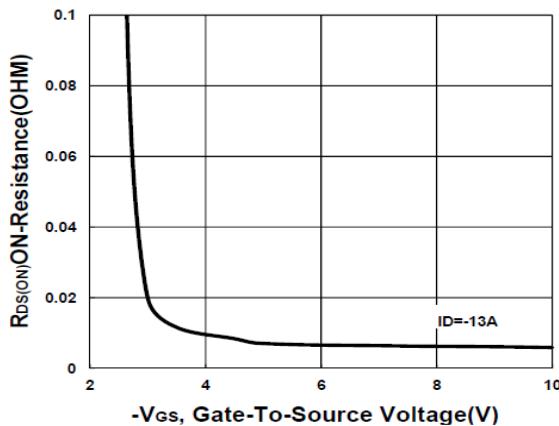
**Gate charge Characteristics**



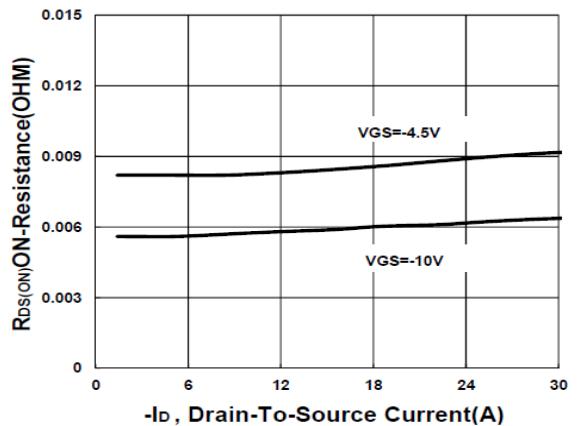
**Capacitance Characteristic**



**On-Resistance VS Gate-To-Source**



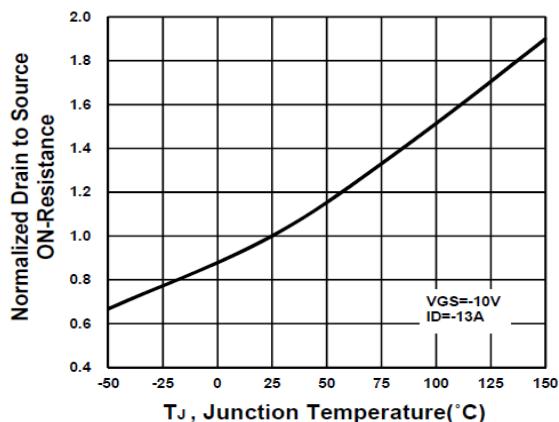
**On-Resistance VS Drain Current**



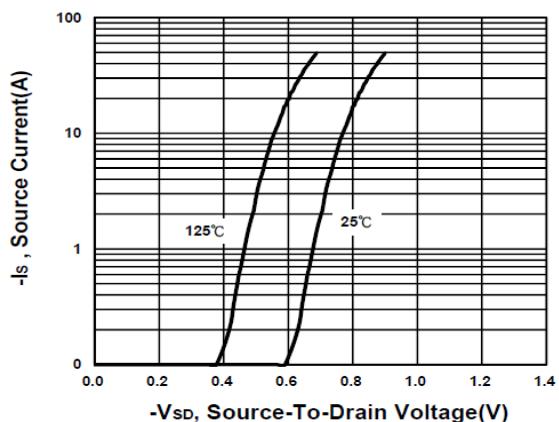
## PK501BA

### P-Channel Logic Level Enhancement Mode MOSFET

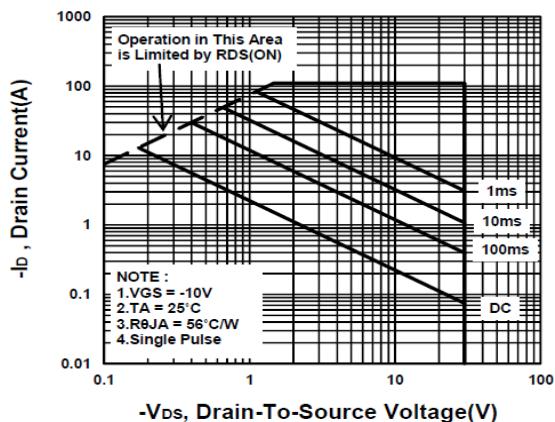
On-Resistance VS Temperature



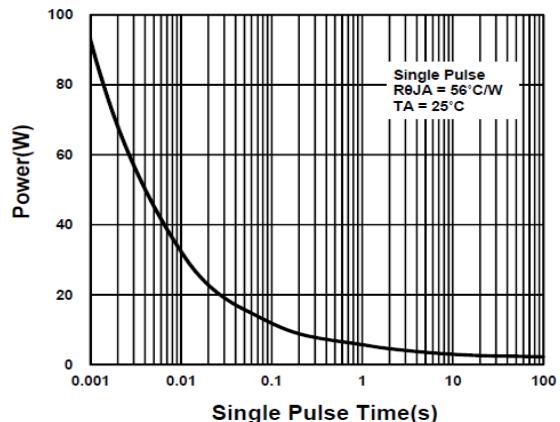
Source-Drain Diode Forward Voltage



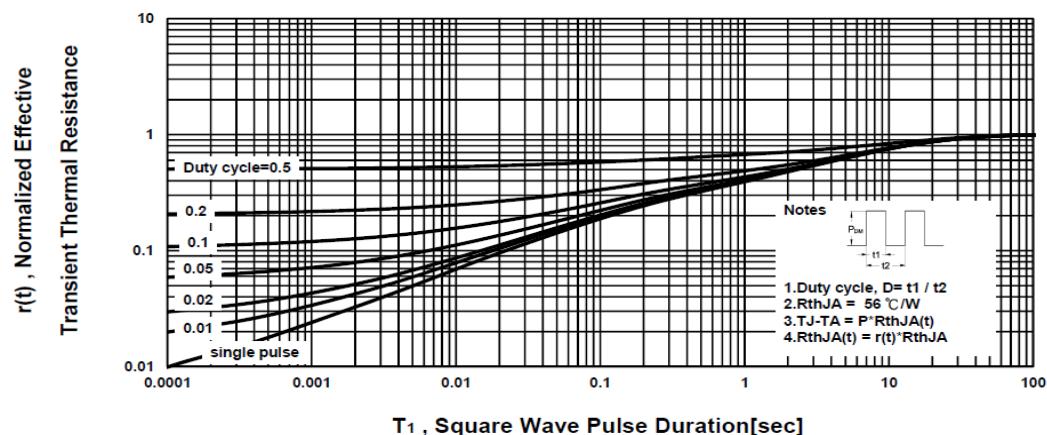
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



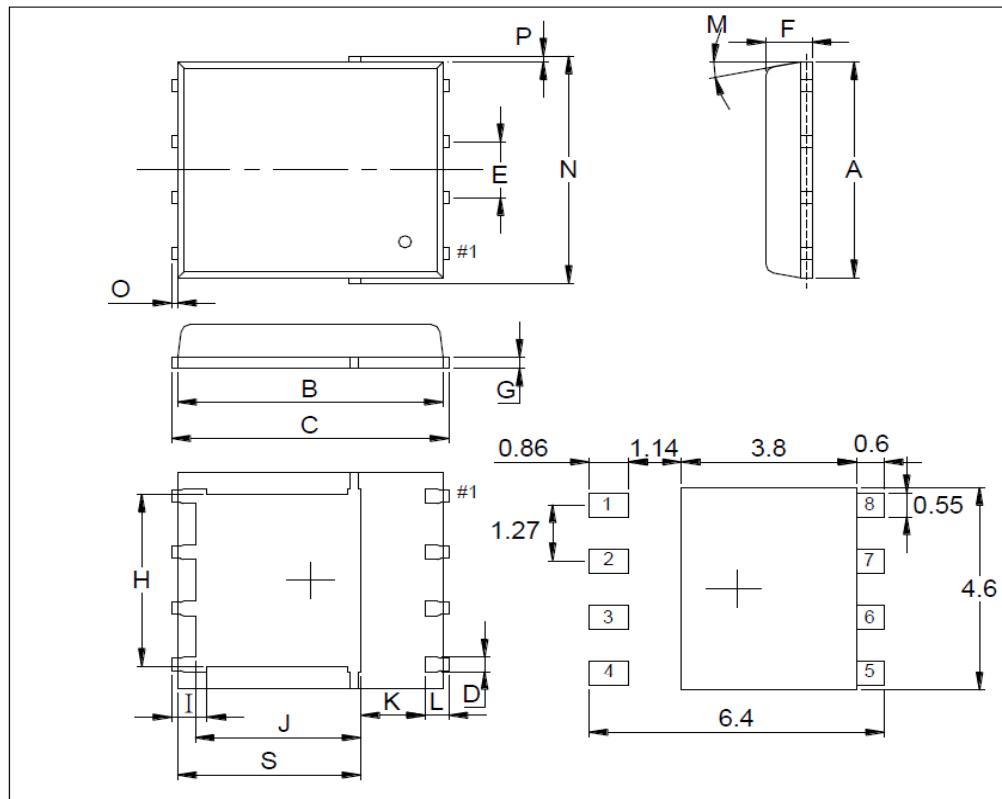
## PK501BA

### P-Channel Logic Level Enhancement Mode MOSFET

#### Package Dimension

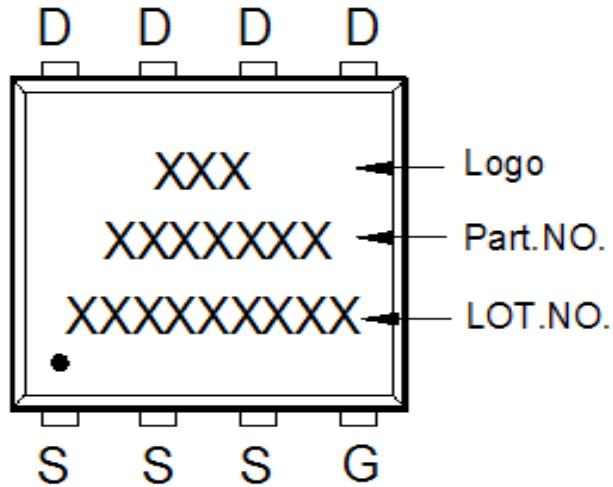
#### PDFN 5x6P MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8		5.15	J	3.34		3.9
B	5.42		5.9	K	0.9		
C	5.9		6.35	L	0.38		0.711
D	0.3		0.51	M	0°		12°
E	1.17	1.27	1.37	N	4.8		5.4
F	0.8	1	1.2	O	0.05		0.36
G	0.15		0.35	P	0.05		0.25
H	3.67		4.31	S	3.73		4.19
I	0.38		0.71				

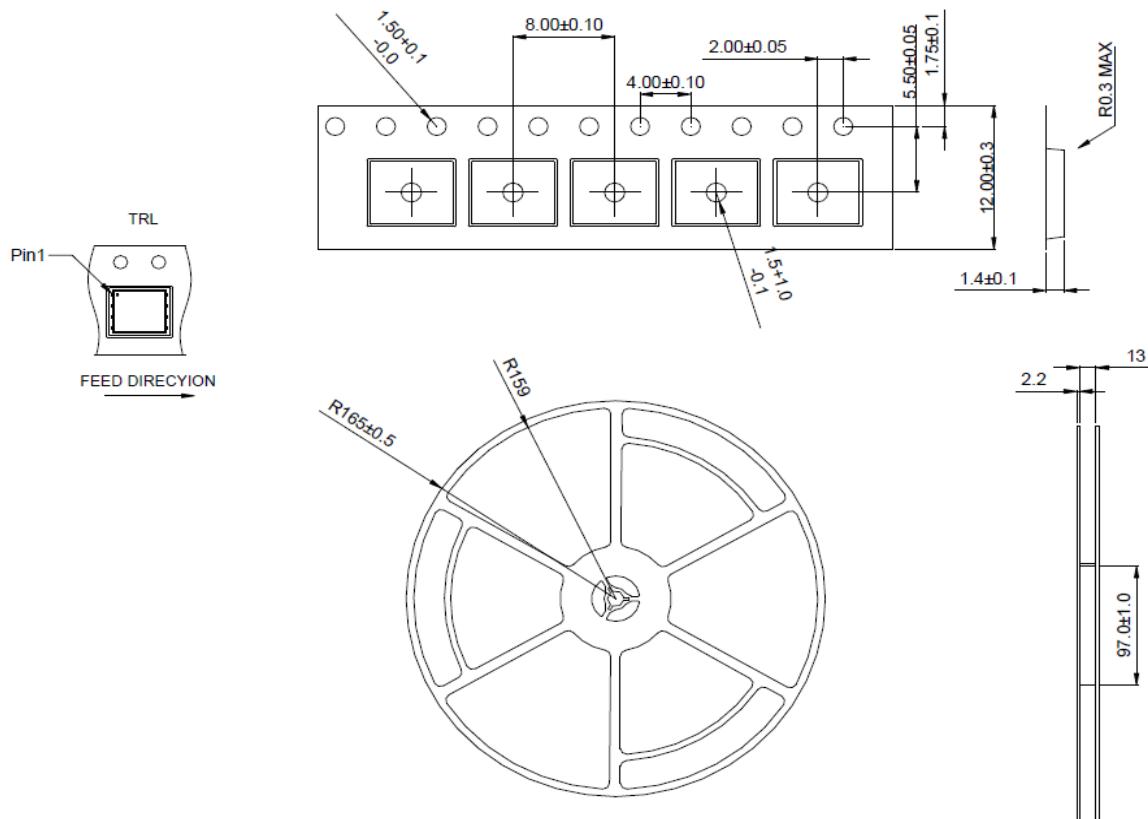


## PK501BA P-Channel Logic Level Enhancement Mode MOSFET

### A. Marking Information



### B. Tape&Reel Information: 3000pcs/Reel

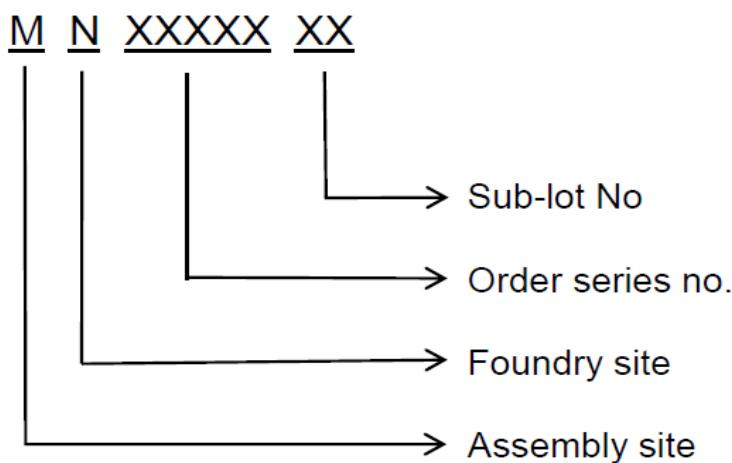


## **PK501BA**

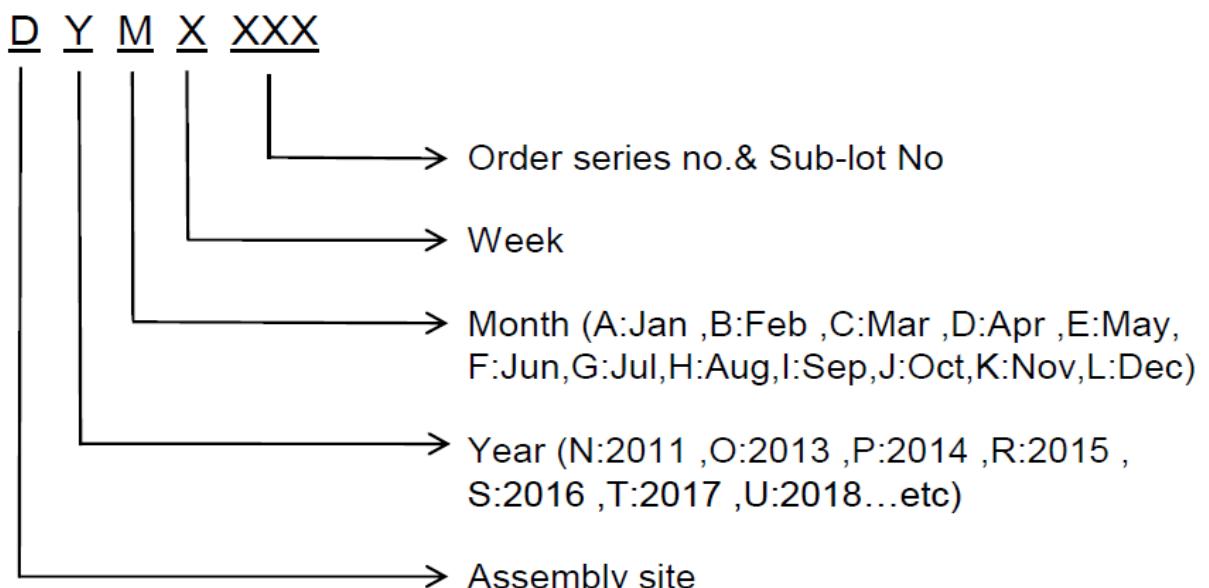
### **P-Channel Logic Level Enhancement Mode MOSFET**

#### **C. Lot No.&Date Code rule**

##### **1. Lot No.**



##### **2. Date Code**





## PK501BA P-Channel Logic Level Enhancement Mode MOSFET

### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm		
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)		
3	U-NIKC	Height: 4 mm		
4	Package	Height: 2 mm		
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12		
6	Device	Height: 3 mm (Max: 16 Digit)		
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot		
8	D/C	Height: 3 mm (Max: 7 Digit)		
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed		
10	RoHS label	<b>RoHS</b> long axis: 12 mm      minor axis: 6 mm bottom color: White Font color: Black      Font style: Arial		
11	Halogen Free label	<b>G</b> Diameter: 10 mm      bottom color: Green Font color: Black      Font style: Arial		
12	Scan information	Device / Lot / D/C / QTY , Insert “ / ” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least		